

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#2/a
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Sunder

In re Patent Application of:
ZENG

Serial No. **Not yet assigned**

Filing Date: **Herewith**

For: **SEMICONDUCTOR DEVICE HAVING
REDUCED EFFECTIVE SUBSTRATE
RESISTIVITY AND ASSOCIATED
METHODS**

) Examiner: A. Wilson

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) Art Unit: 2815

)

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PRELIMINARY AMENDMENT *Eric Link*
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Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to the calculation of fees and examination of
the present application, please enter the amendments and
remarks set out below.

In the Claims:

Please cancel Claims 1-51

Please add new Claims 52-75.

52. A method for making a semiconductor device
comprising a semiconductor substrate having a lowered
effective electrical resistivity, the method comprising:
forming at least one device active region in the
semiconductor substrate adjacent a first surface thereof;

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